

DOSEMI

IGBT

DG75A08TDFS

750V/75A IGBT with Diode

General Description

DOSEMI IGBT Power Discrete provides ultra low conduction loss as well as low switching loss. They are designed for the applications such as solar power.

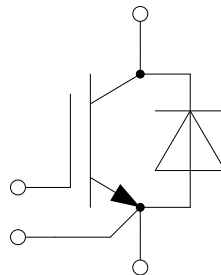
Features

- Low $V_{CE(sat)}$ Fast IGBT technology
- Low switching loss
- Maximum junction temperature 175°C
- $V_{CE(sat)}$ with positive temperature coefficient
- Fast & soft reverse recovery anti-parallel FWD

Typical Applications

- Solar power
- UPS
- 3-level-application

Equivalent Circuit Schematic



Type	Package	Marking	Shipping
DG75A08TDFS	TO-247PLUS-4L	DG75A08TDFS	30Units/Tube

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted**IGBT**

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	750	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^\circ\text{C}$	100	A
	@ $T_C=100^\circ\text{C}$	75	A
I_{CRM}	Repetitive Peak Collector Current tp limited by T_{vjop}	225	A
P_D	Maximum Power Dissipation @ $T_{vj}=175^\circ\text{C}$	378	W

Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	750	V
I_F	Diode Continuous Forward Current @ $T_C=25^\circ\text{C}$	100	A
	@ $T_C=100^\circ\text{C}$	75	A
I_{FRM}	Repetitive Peak Forward Current tp limited by T_{vjop}	225	A

Discrete

Symbol	Description	Values	Unit
T_{vjop}	Operating Junction Temperature	-40 to +175	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_S	Soldering Temperature, 1.6mm from case for 10s	260	$^\circ\text{C}$

IGBT Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=75\text{A}, V_{GE}=15\text{V}, T_{vj}=25^{\circ}\text{C}$		1.45	1.90	V
		$I_C=75\text{A}, V_{GE}=15\text{V}, T_{vj}=150^{\circ}\text{C}$		1.80		
		$I_C=75\text{A}, V_{GE}=15\text{V}, T_{vj}=175^{\circ}\text{C}$		1.90		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=1.5\text{mA}, V_{CE}=V_{GE}, T_{vj}=25^{\circ}\text{C}$	3.5	4.0	4.5	V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_{vj}=25^{\circ}\text{C}$			200	μA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_{vj}=25^{\circ}\text{C}$			100	nA
R_{Gint}	Internal Gate Resistance			0		Ω
C_{ies}	Input Capacitance			2.89		nF
C_{res}	Reverse Transfer Capacitance	$V_{CE}=25\text{V}, f=100\text{kHz}, V_{GE}=0\text{V}$		0.01		nF
C_{oes}	Output Capacitance			0.77		nF
Q_G	Gate Charge	$V_{GE}=-10\dots+15\text{V}$		0.17		μC
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=400\text{V}, I_C=75\text{A}, R_G=15\Omega, L_s=40\text{nH}, V_{GE}=\pm 15\text{V}, T_{vj}=25^{\circ}\text{C}$		32		ns
t_r	Rise Time			26		ns
$t_{d(off)}$	Turn-Off Delay Time			67		ns
t_f	Fall Time			66		ns
E_{on}	Turn-On Switching Loss			0.79		mJ
E_{off}	Turn-Off Switching Loss			1.38		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=400\text{V}, I_C=75\text{A}, R_G=15\Omega, L_s=40\text{nH}, V_{GE}=\pm 15\text{V}, T_{vj}=150^{\circ}\text{C}$		34		ns
t_r	Rise Time			28		ns
$t_{d(off)}$	Turn-Off Delay Time			76		ns
t_f	Fall Time			116		ns
E_{on}	Turn-On Switching Loss			1.34		mJ
E_{off}	Turn-Off Switching Loss			1.85		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=400\text{V}, I_C=75\text{A}, R_G=15\Omega, L_s=40\text{nH}, V_{GE}=\pm 15\text{V}, T_{vj}=175^{\circ}\text{C}$		35		ns
t_r	Rise Time			29		ns
$t_{d(off)}$	Turn-Off Delay Time			76		ns
t_f	Fall Time			138		ns
E_{on}	Turn-On Switching Loss			1.51		mJ
E_{off}	Turn-Off Switching Loss			1.96		mJ

Diode Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=75\text{A}, V_{GE}=0\text{V}, T_{vj}=25^\circ\text{C}$		1.60	2.05	V
		$I_F=75\text{A}, V_{GE}=0\text{V}, T_{vj}=150^\circ\text{C}$		1.60		
		$I_F=75\text{A}, V_{GE}=0\text{V}, T_{vj}=175^\circ\text{C}$		1.60		
Q_r	Recovered Charge	$V_R=400\text{V}, I_F=75\text{A},$ $-di/dt=3130\text{A}/\mu\text{s}, L_s=40\text{nH},$ $V_{GE}=-15\text{V}, T_{vj}=25^\circ\text{C}$		3.77		μC
t_{rr}	Recovered Time			62		ns
I_{RM}	Peak Reverse Recovery Current			98		A
E_{rec}	Reverse Recovery Energy			0.58		mJ
Q_r	Recovered Charge	$V_R=400\text{V}, I_F=75\text{A},$ $-di/dt=2780\text{A}/\mu\text{s}, L_s=40\text{nH},$ $V_{GE}=-15\text{V}, T_{vj}=150^\circ\text{C}$		5.75		μC
t_{rr}	Recovered Time			87		ns
I_{RM}	Peak Reverse Recovery Current			114		A
E_{rec}	Reverse Recovery Energy			1.02		mJ
Q_r	Recovered Charge	$V_R=400\text{V}, I_F=75\text{A},$ $-di/dt=2702\text{A}/\mu\text{s}, L_s=40\text{nH},$ $V_{GE}=-15\text{V}, T_{vj}=175^\circ\text{C}$		7.59		μC
t_{rr}	Recovered Time			141		ns
I_{RM}	Peak Reverse Recovery Current			116		A
E_{rec}	Reverse Recovery Energy			1.62		mJ

Discrete Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
R_{thJC}	Junction-to-Case (per IGBT)			0.396	K/W
	Junction-to-Case (per Diode)			0.375	
R_{thJA}	Junction-to-Ambient		40		K/W

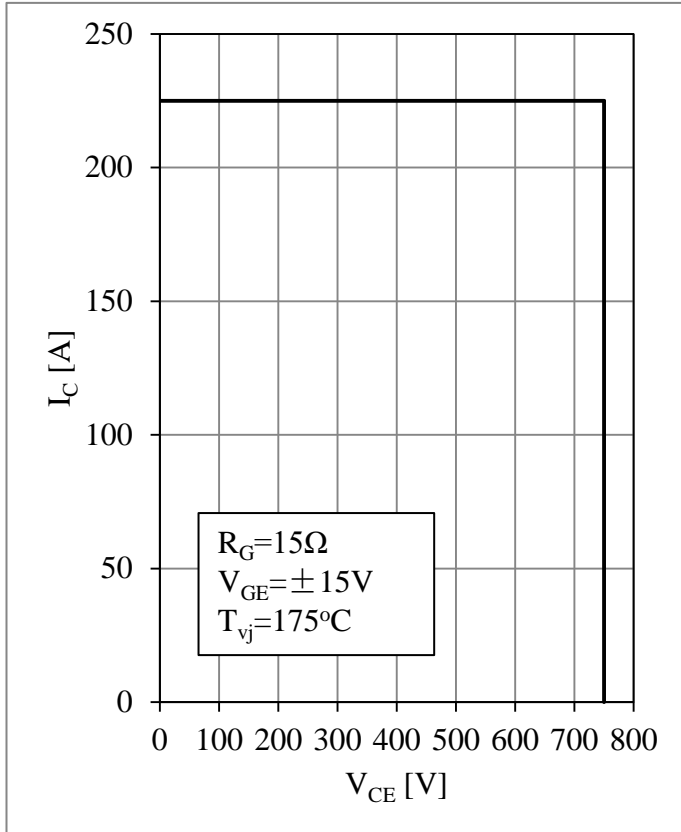


Fig 1. RBSOA

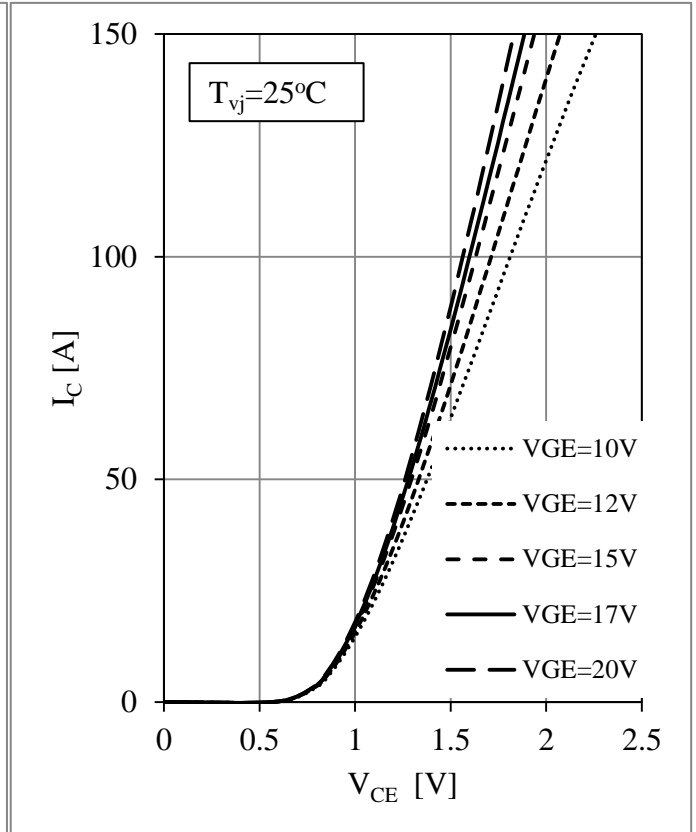


Fig 2. IGBT Output Characteristics

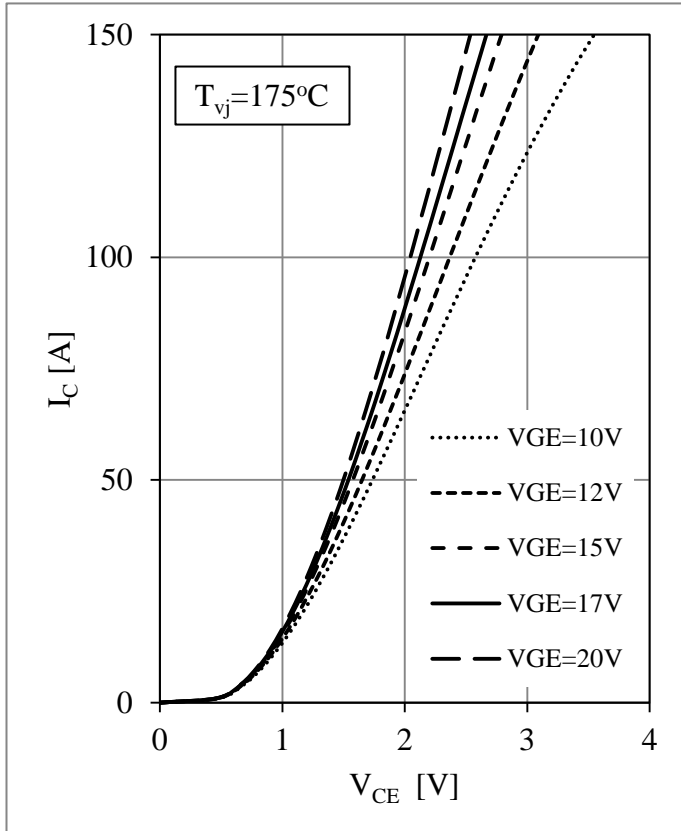


Fig 3. IGBT Output Characteristics

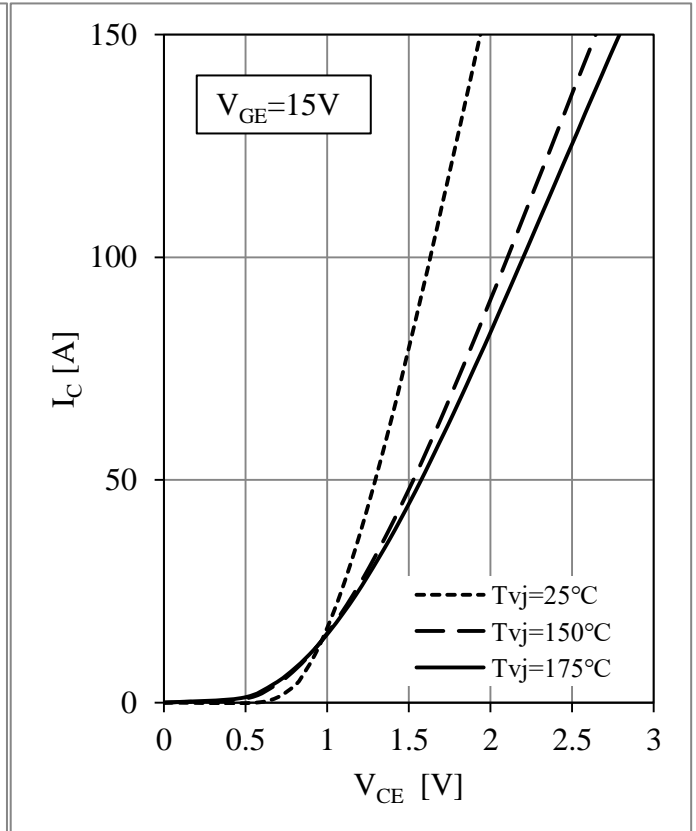


Fig 4. IGBT Output Characteristics

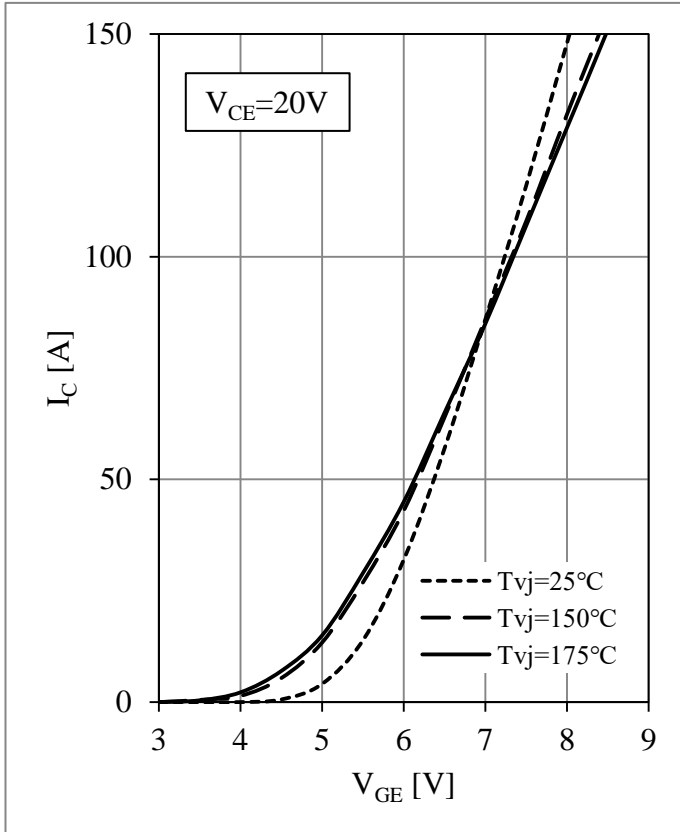


Fig 5. IGBT Transfer Characteristics

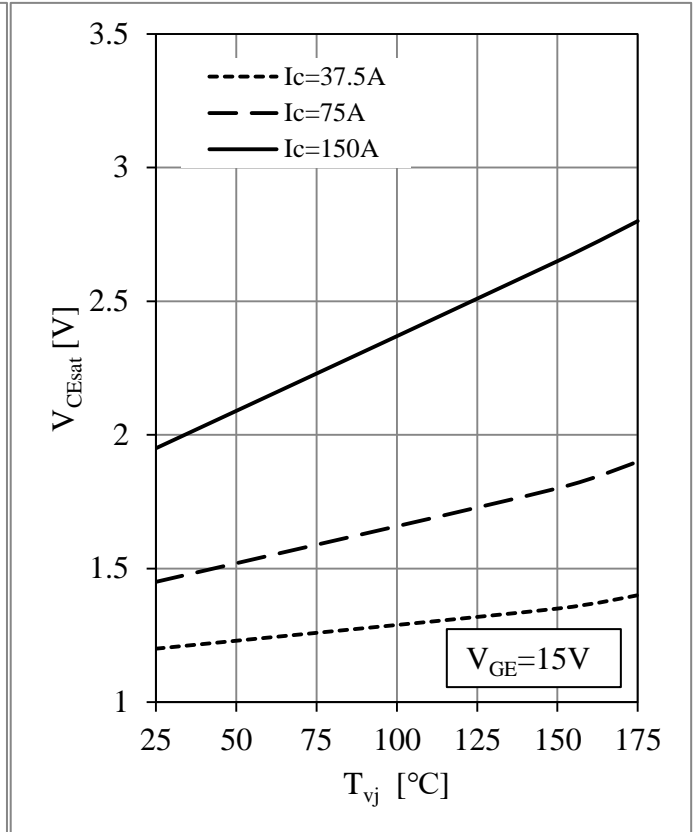


Fig 6. Collector-emitter saturation voltage vs T_{vj}

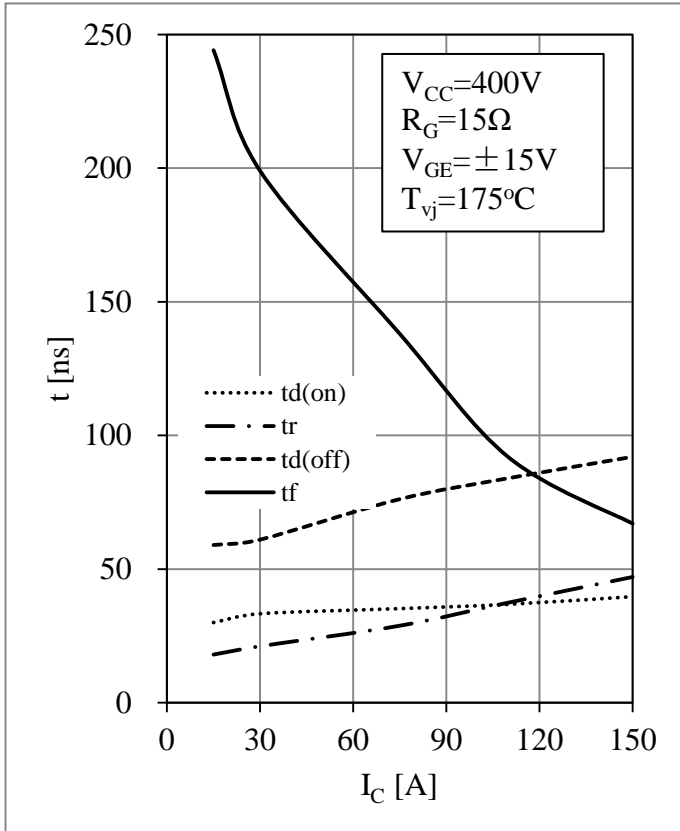


Fig 7. IGBT Switching Times as I_c

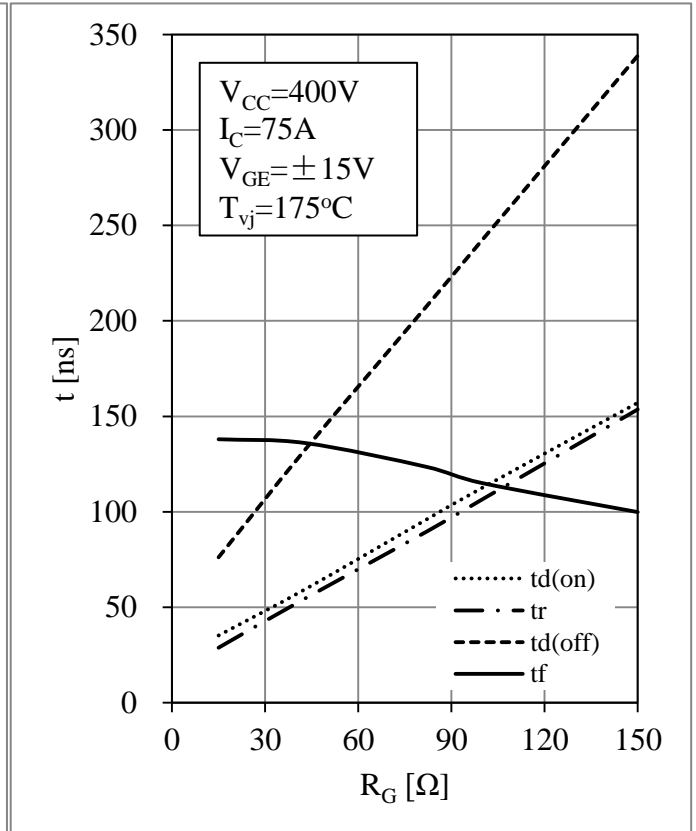


Fig 8. IGBT Switching Times as R_G

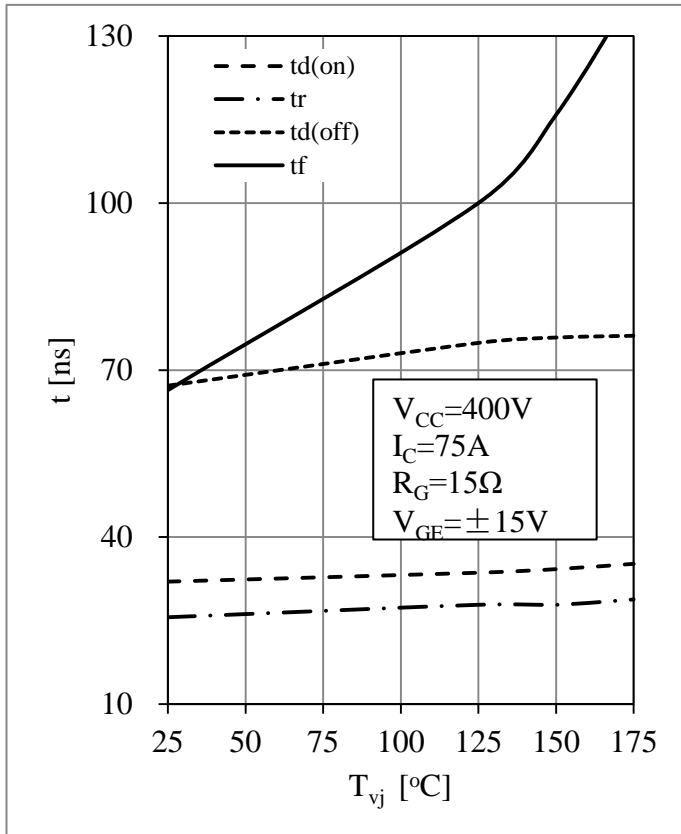


Fig 9. IGBT Switching Times as. T_{vj}

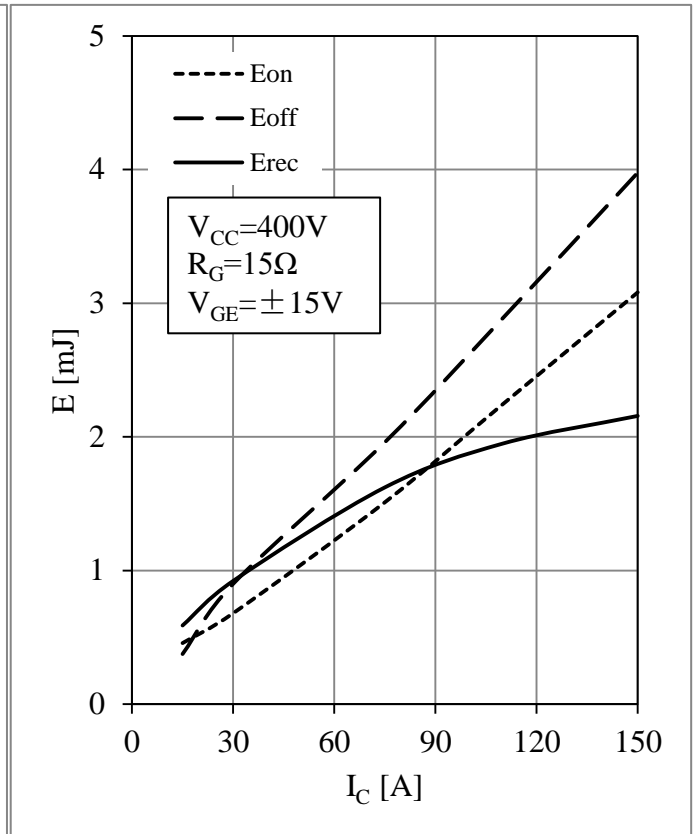


Fig 10. Switching Energy Loss vs. I_C

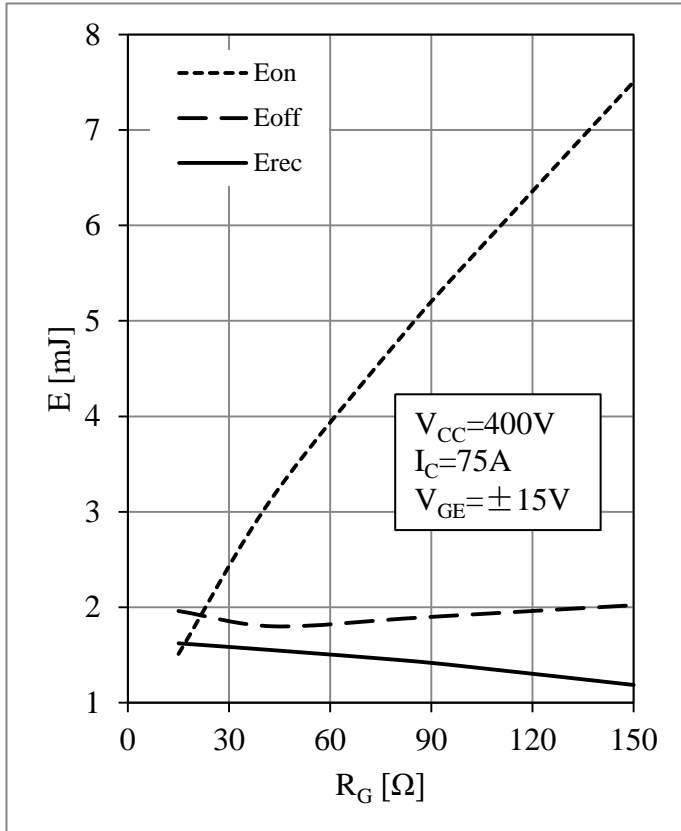


Fig 11. Switching Energy Loss vs. R_G

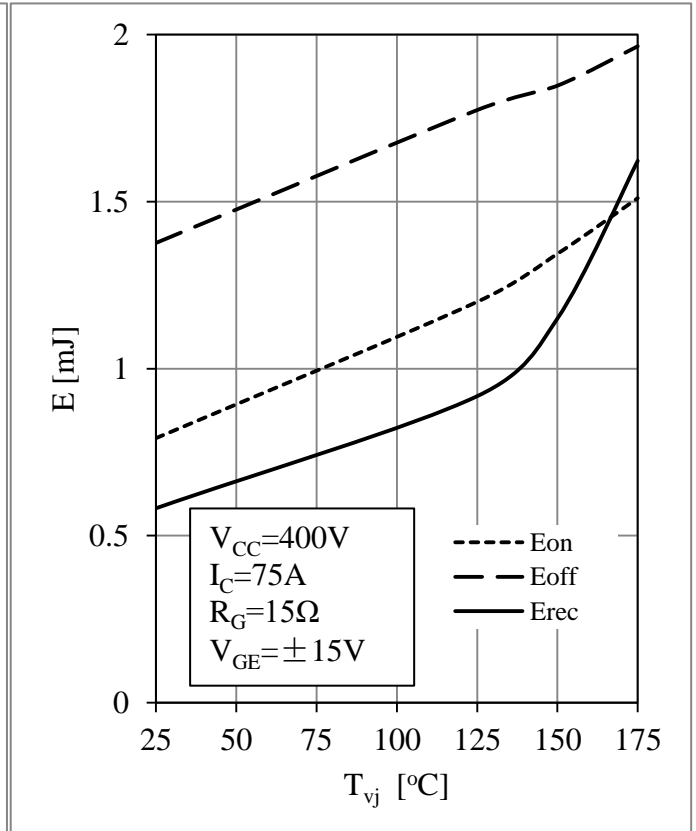


Fig 12. Switching Energy Loss vs. T_{vj}

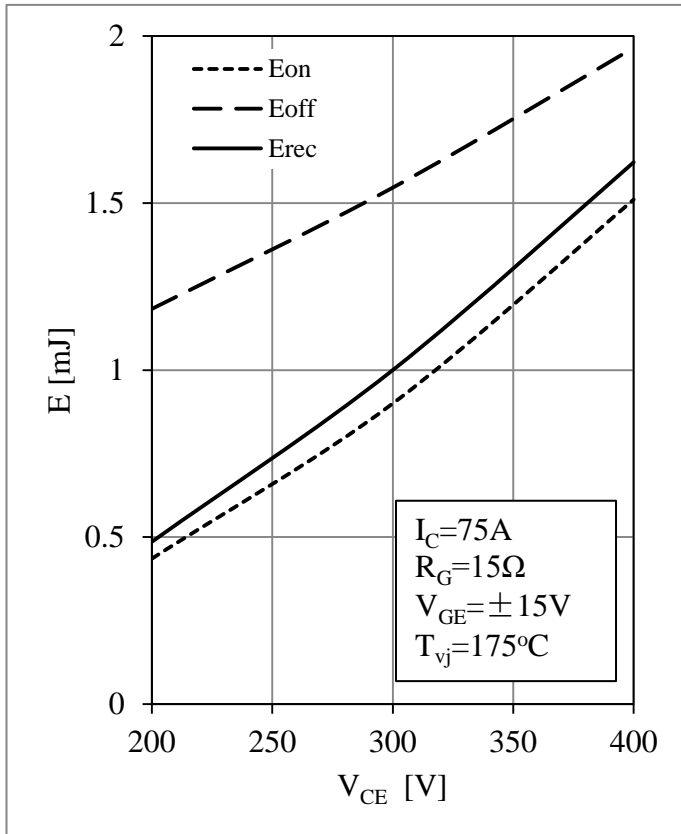


Fig 13. Switching Energy Loss vs. V_{CE}

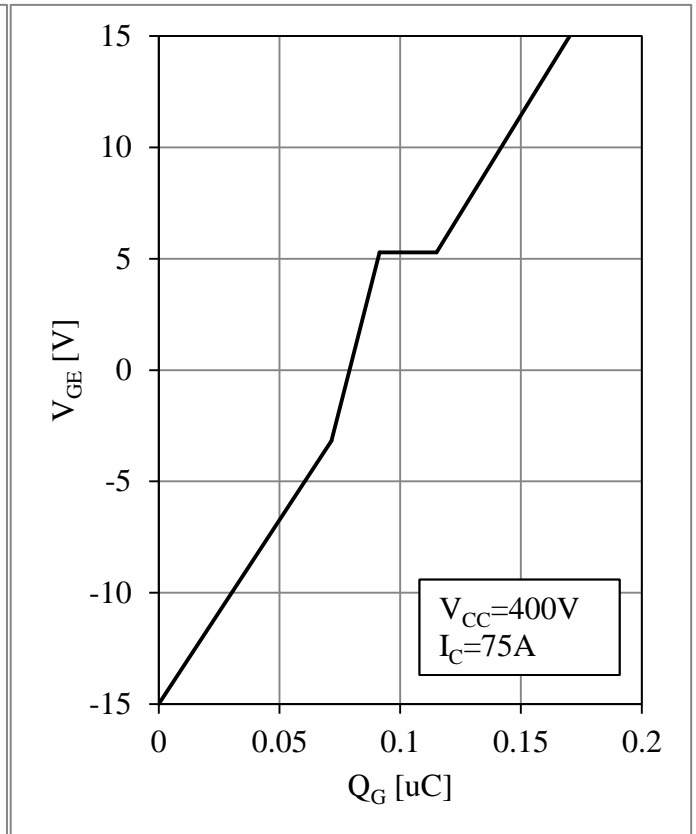


Fig 14. IGBT Gate Charge Characteristic

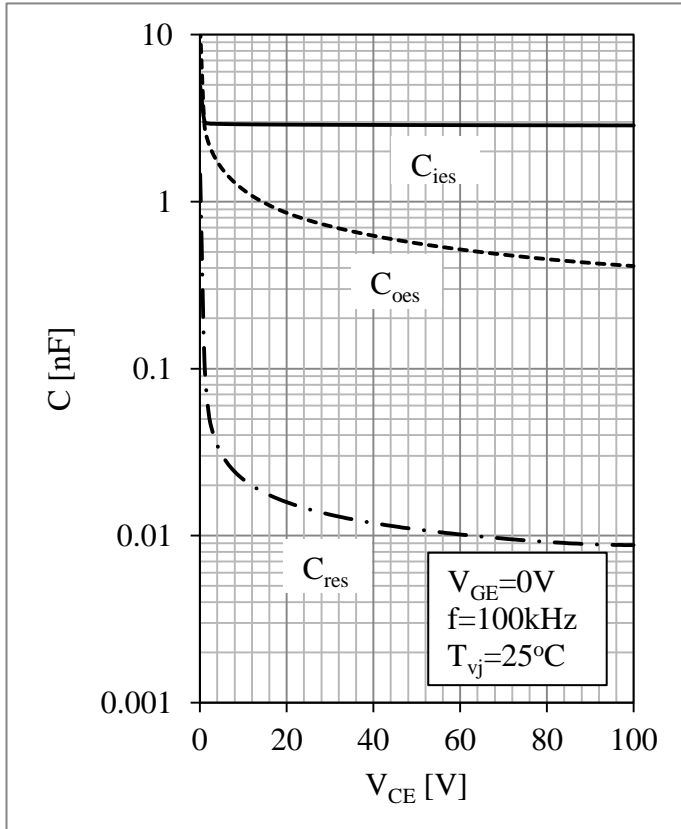


Fig 15. IGBT Capacity Characteristic

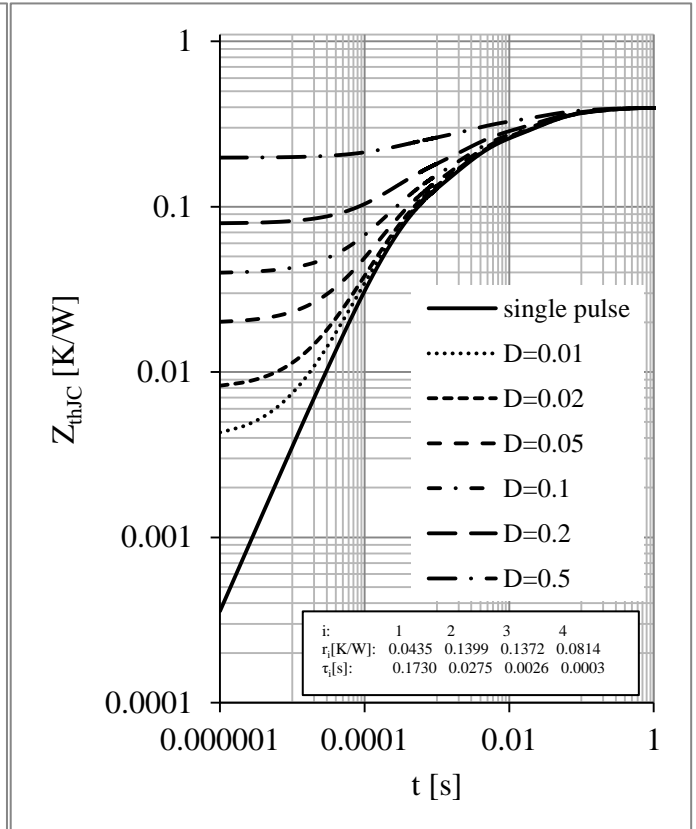


Fig 16. IGBT Transient Thermal Impedance

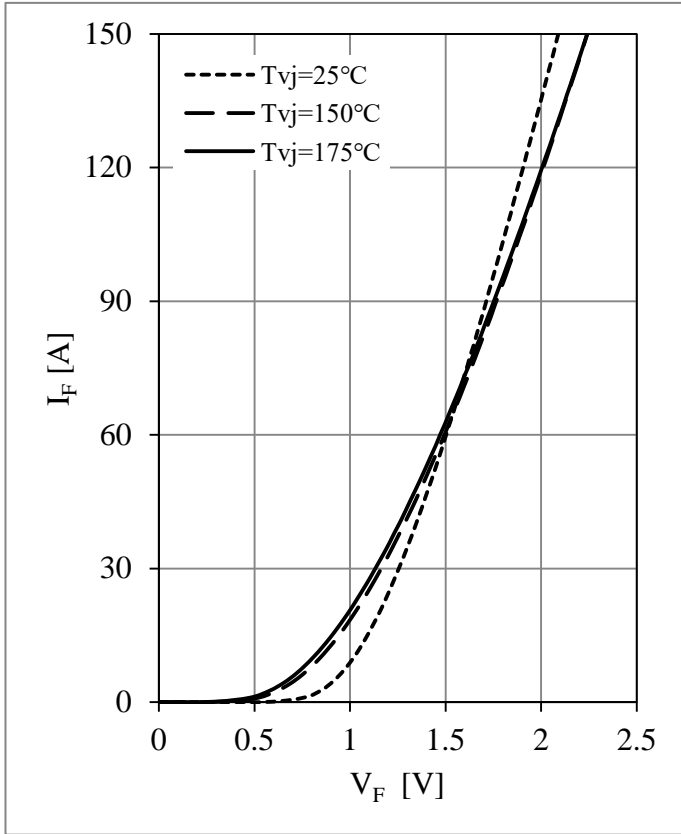


Fig 17. Diode Forward Characteristics

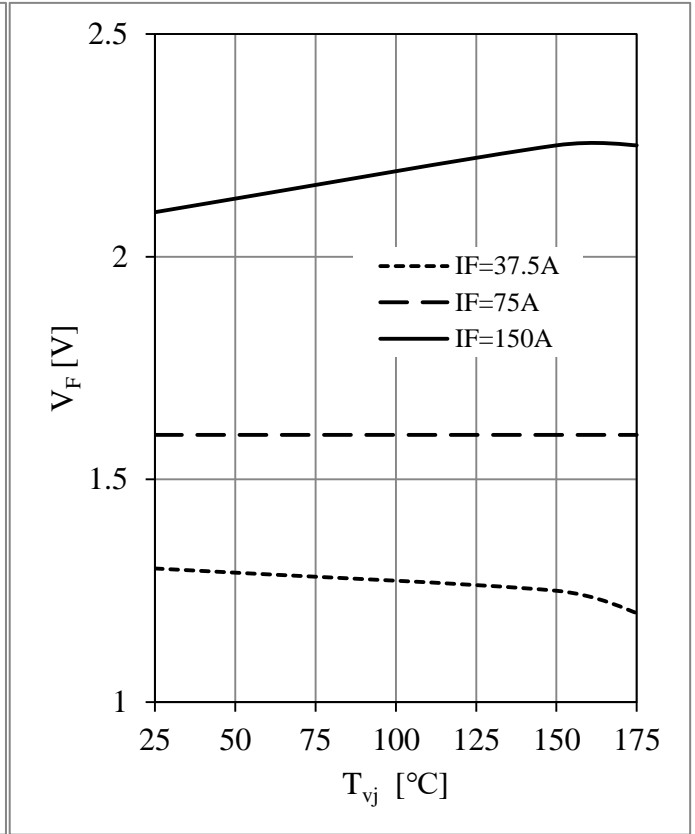


Fig 18. Diode Forward Voltage V_F Vs T_{vj}

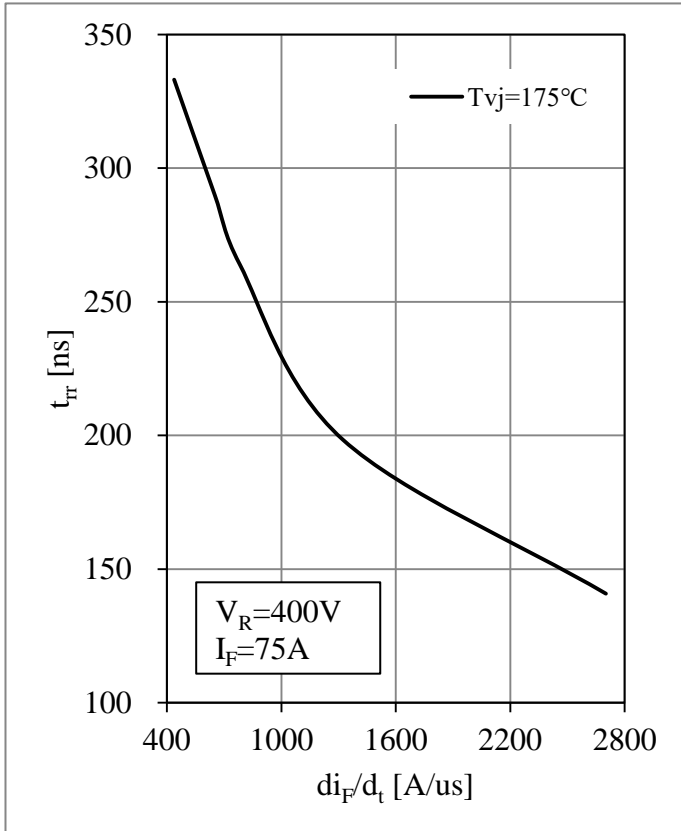


Fig 19. Reverse Recovery Time vs. di_F/d_t

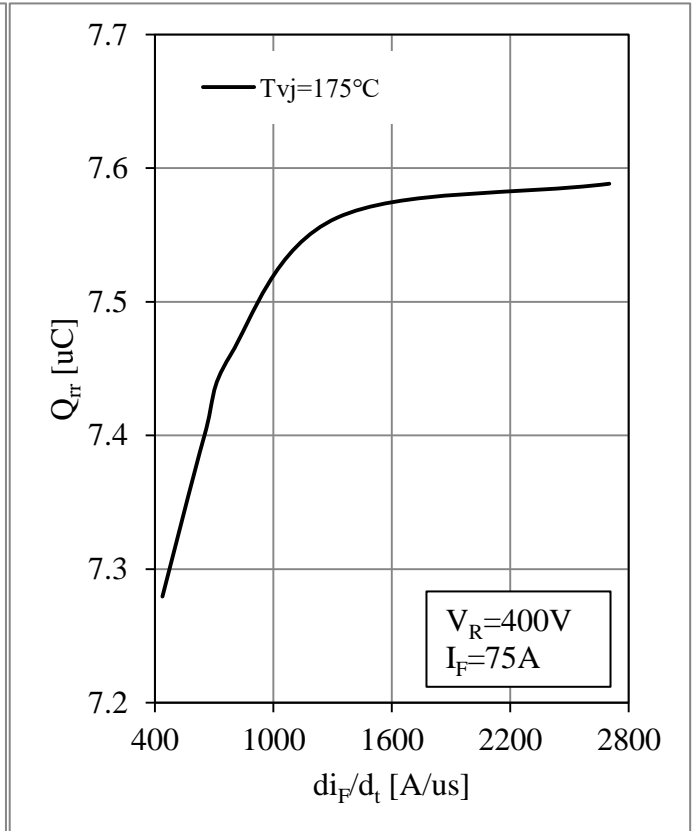


Fig 20. Reverse Recovery Charge vs. di_F/d_t

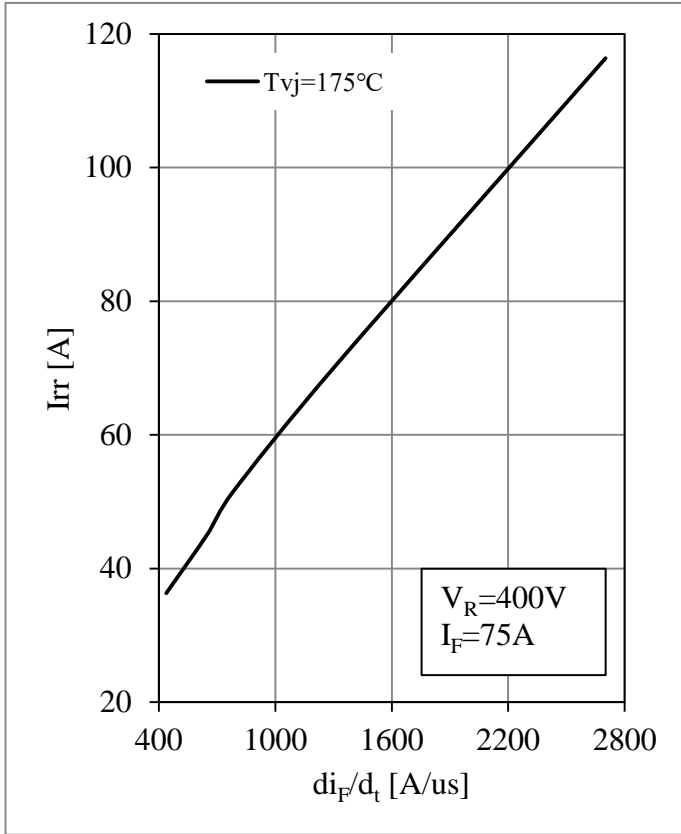


Fig 21. Reverse Recovery Current vs. di_F/dt

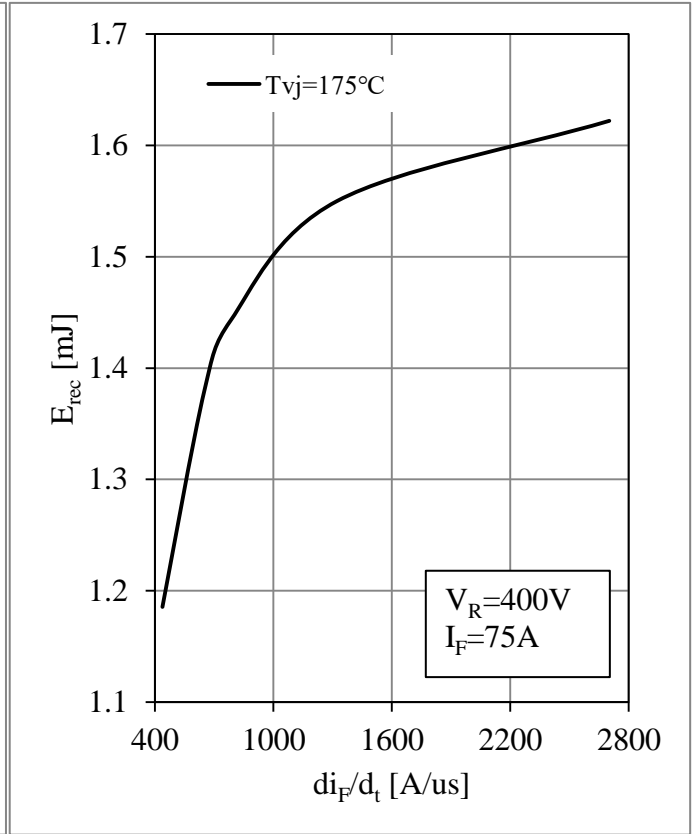


Fig 22. Reverse Energy Losses vs. di_F/dt

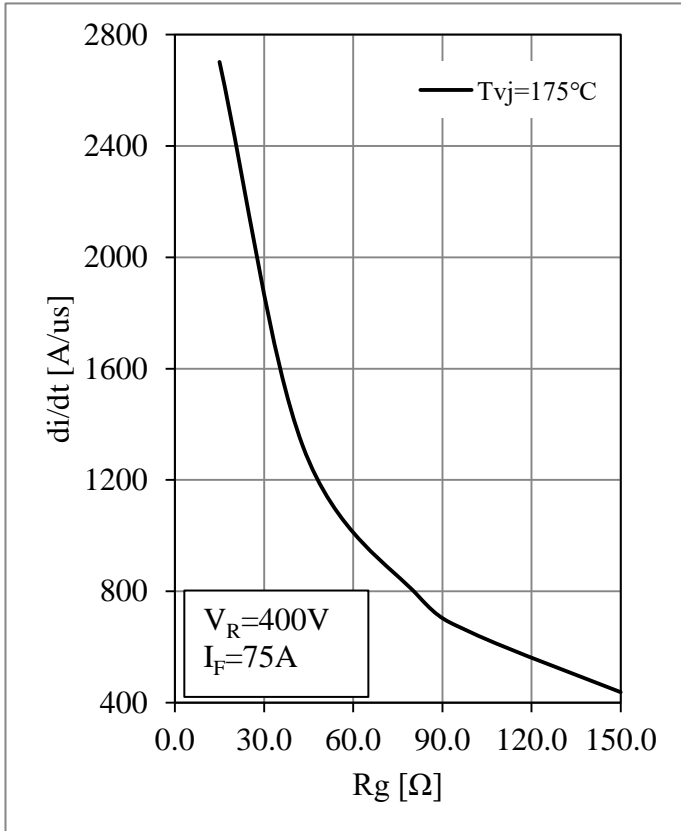


Fig 23. di_F/dt vs R_g

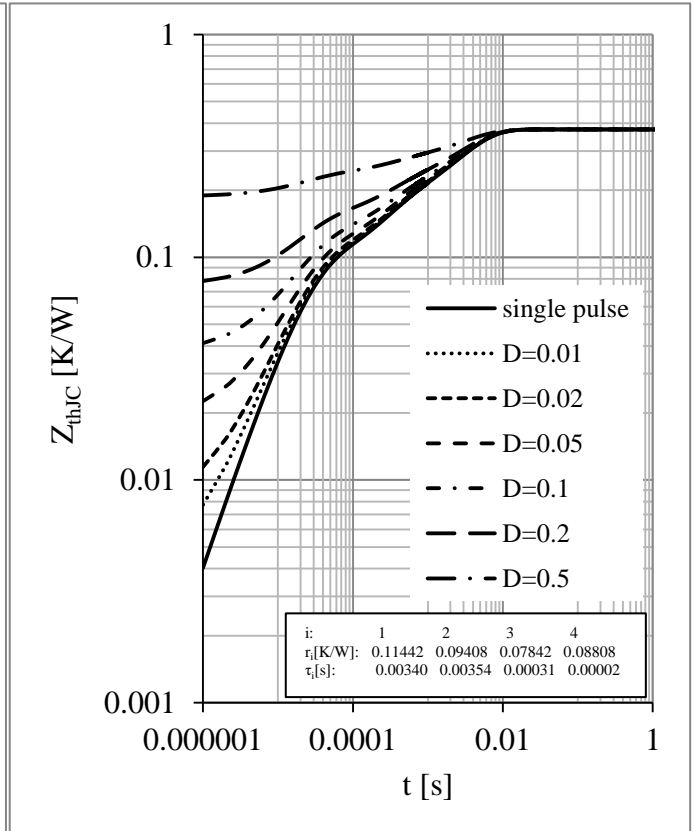
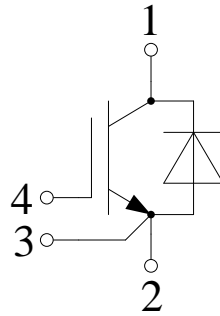


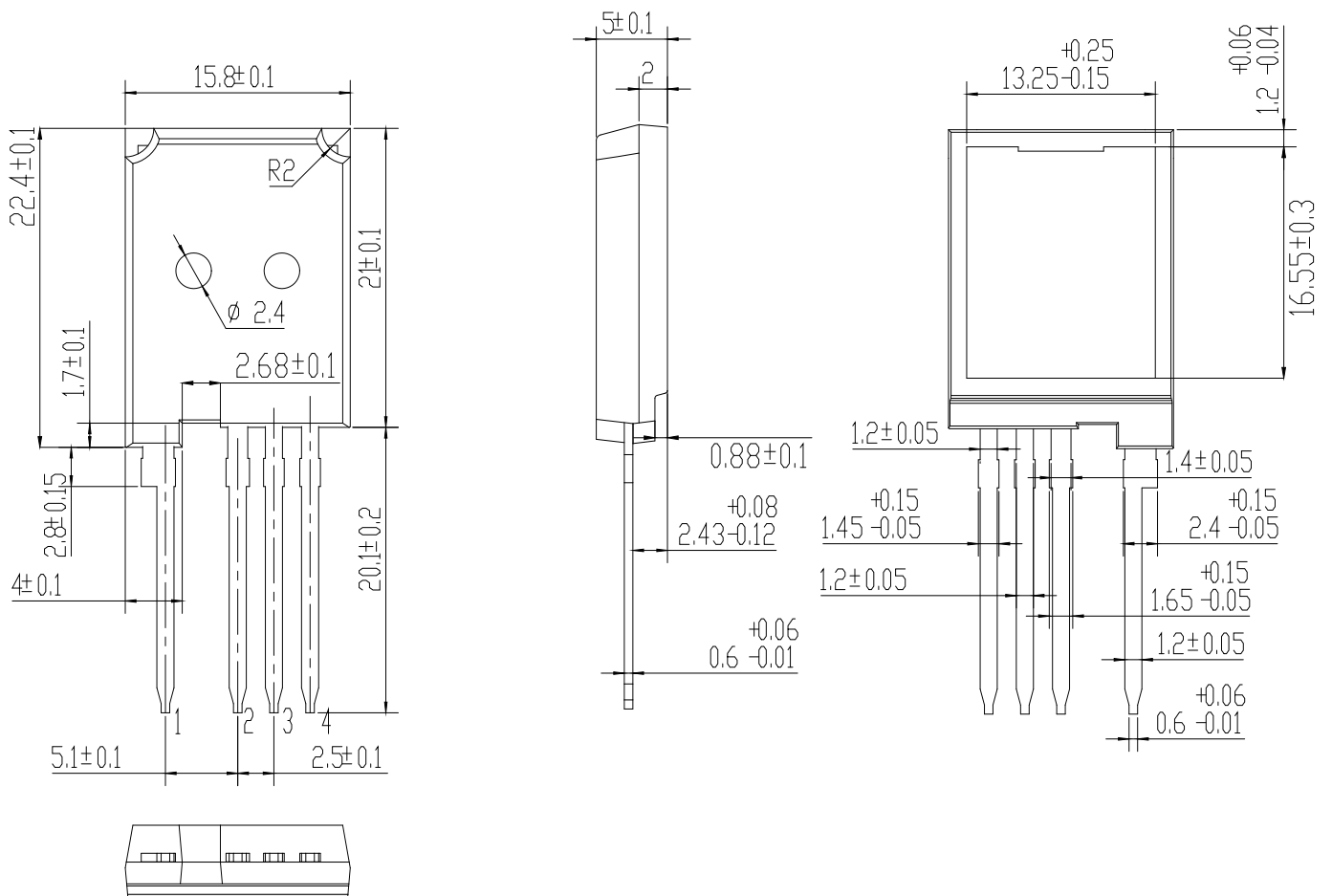
Fig 24. Diode Transient Thermal Impedance

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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